Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.175”**

**ANODE**

**.163 x .163”**

**.175”**

**Top Material: Al**

**Backside Material: TiNiAg**

**Bond Pad Size: .163 x .163”**

**Backside Potential: CATHODE**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .175” X .175” DATE: 11/10/21**

**MFG: SILICON SUPPLIES THICKNESS .011” P/N: 1N6391**

**DG 10.1.2**

#### Rev B, 7/1